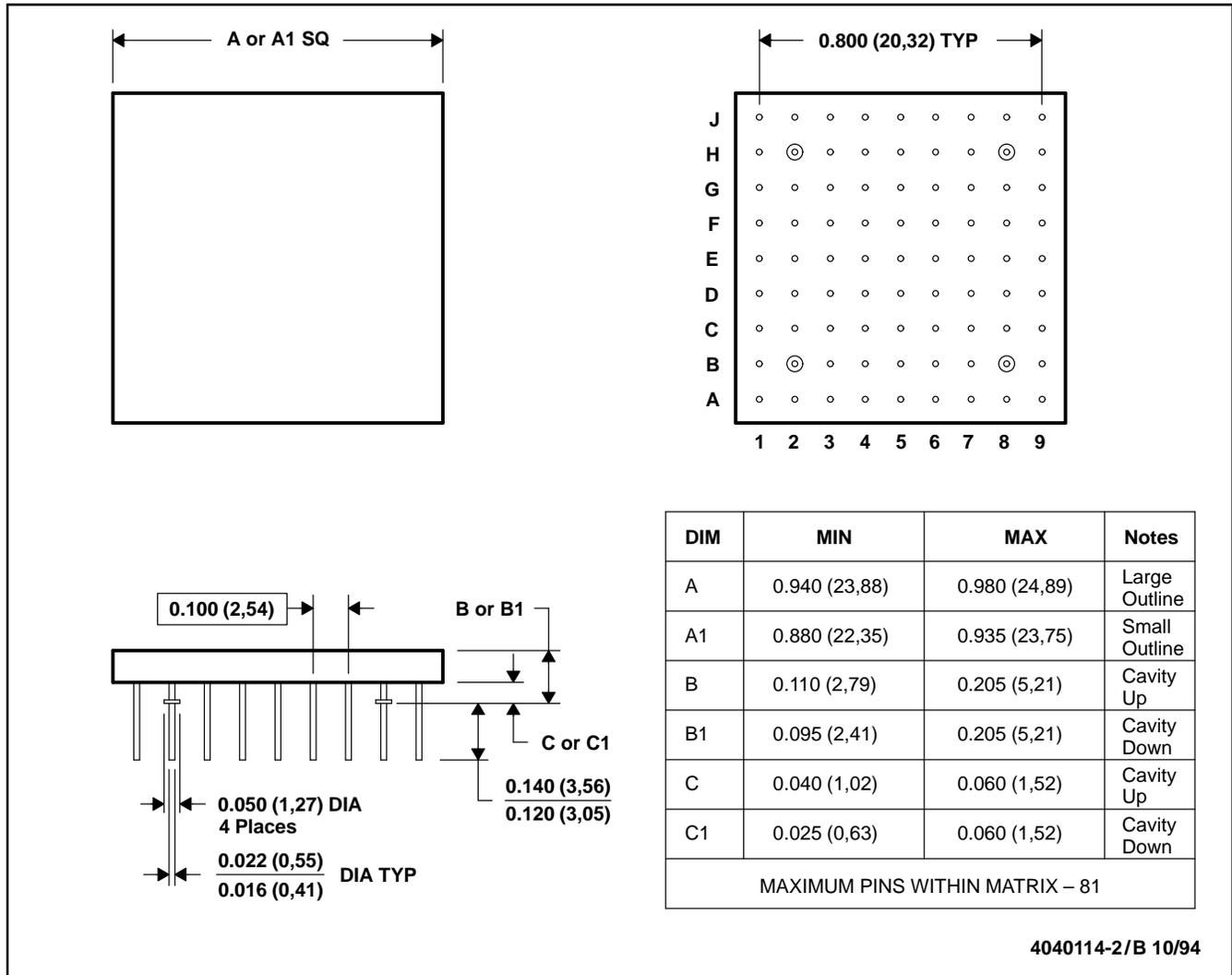


GA-GB (S-CPGA-P9 X 9)

CERAMIC PIN GRID ARRAY PACKAGE



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Index mark may appear on top or bottom depending on package vendor.
 D. Pins are located within 0.005 (0,13) radius of true position relative to each other at maximum material condition and within 0.015 (0,38) radius relative to the center of the ceramic.
 E. This package can be hermetically sealed with metal lids or with ceramic lids using glass frit.
 F. The pins can be gold plated or solder dipped.
 G. Falls within MIL-STD-1835 CMGA1-PN and CMGA13-PN and JEDEC MO-067AA and MO-066AA, respectively

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